# BLC8G20LS-400AV

# Power LDMOS transistor Rev. 4 — 24 November 2017

**AMMPLEON** 

Product data sheet

#### **Product profile** 1.

#### 1.1 General description

400 W LDMOS packaged asymmetric Doherty power transistor for base station applications at frequencies from 1800 MHz to 2000 MHz.

#### Typical performance

Typical RF performance at  $T_{case} = 25$  °C in an asymmetrical Doherty production test circuit.  $V_{DS}$  = 32 V;  $I_{Dq}$  = 800 mA (main);  $V_{GS(amp)peak}$  = 0.4 V, unless otherwise specified.

Test signal	f	V <sub>DS</sub>	P <sub>L(AV)</sub>	G <sub>p</sub>	η <sub>D</sub>	ACPR
	(MHz)	(V)	(W)	(dB)	(%)	(dBc)
1-carrier W-CDMA	1805 to 1880	32	85	15.5	44	-31 <u>[1]</u>
	1930 to 1990	32	85	15.5	44	-35 <u>[1]</u>

<sup>[1]</sup> Test signal: 1-carrier W-CDMA; 3GPP test model 1; 64 DPCH; PAR = 9.6 dB at 0.01% probability on CCDF.

#### 1.2 Features and benefits

- Excellent ruggedness
- Excellent electrical stability
- Suitable for conventional and inverted Doherty
- High efficiency
- Low thermal resistance providing excellent thermal stability
- Lower output capacitance for improved performance in Doherty applications
- Designed for low memory effects providing excellent digital pre-distortion capability
- Internally matched for ease of use
- Integrated ESD protection
- Compliant to Directive 2002/95/EC, regarding Restriction of Hazardous Substances (RoHS)

### 1.3 Applications

RF power amplifiers for base stations and multi carrier applications in the 1800 MHz to 2000 MHz frequency range

# 2. Pinning information

Table 2. Pinning

Pin	Description		Simplified outline	Graphic symbol
1	drain2 (peak)			0.7
2	drain1 (main)		7 2 1 6	2, 7
3	gate1 (main)		5	
4	gate2 (peak)		3 4	3——5
5	source	[1]		4—
6	video decoupling (peak)			<b>'</b> Ь¬
7	video decoupling (main)			1, 6 aaa-014884

<sup>[1]</sup> Connected to flange.

# 3. Ordering information

Table 3. Ordering information

Type number	Packag	ackage					
	Name Description						
BLC8G20LS-400AV	-	Air cavity plastic earless flanged package; 6 leads	SOT1258-1				

# 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>DS</sub>	drain-source voltage		-	65	V
V <sub>GS(amp)main</sub>	main amplifier gate-source voltage		-0.5	+13	V
V <sub>GS(amp)peak</sub>	peak amplifier gate-source voltage		-0.5	+13	V
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature	<u>[1]</u>	-	225	°C

<sup>[1]</sup> Continuous use at maximum temperature will affect the reliability, for details refer to the online MTF calculator.

# 5. Recommended operating conditions

Table 5. Operating conditions

Symbol	Parameter	Conditions	Min	Max	Unit
T <sub>case</sub>	case temperature		-40	+125	°C

# 6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Тур	Unit
R <sub>th(j-c)</sub>	thermal resistance from junction to case	V <sub>DS</sub> = 32 V; I <sub>Dq</sub> = 800 mA (main); V <sub>GS(amp)peak</sub> = 0.4 V; T <sub>case</sub> = 80 °C.		
		P <sub>L</sub> = 85 W	0.32	K/W
		P <sub>L</sub> = 110 W	0.31	K/W

### 7. Characteristics

#### Table 7. DC characteristics

 $T_i = 25$  °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Main dev	ice					
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	V <sub>GS</sub> = 0 V; I <sub>D</sub> = 1.8 mA	65	-	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 180 mA	1.5	1.9	2.3	V
$V_{GSq}$	gate-source quiescent voltage	V <sub>DS</sub> = 32 V; I <sub>D</sub> = 800 mA	1.7	2.1	2.5	V
I <sub>DSS</sub>	drain leakage current	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 28 V	-	-	2.8	μΑ
I <sub>DSX</sub>	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 \text{ V}; V_{DS} = 10 \text{ V}$	-	34	-	Α
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 11 V; V <sub>DS</sub> = 0 V	-	-	280	nA
g <sub>fs</sub>	forward transconductance	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 9.0 A	-	13	-	S
R <sub>DS(on)</sub>	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75 \text{ V}; I_D = 6.3 \text{ A}$	-	85	135	mΩ
Peak dev	ice					
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	V <sub>GS</sub> = 0 V; I <sub>D</sub> = 3.0 mA	65	-	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 300 mA	1.5	1.9	2.3	V
$V_{GSq}$	gate-source quiescent voltage	V <sub>DS</sub> = 32 V; I <sub>D</sub> = 1800 mA	1.7	2.1	2.5	V
I <sub>DSS</sub>	drain leakage current	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = 28 V	-	-	2.8	μΑ
I <sub>DSX</sub>	drain cut-off current	$V_{GS} = V_{GS(th)} + 3.75 \text{ V}; V_{DS} = 10 \text{ V}$	-	50	-	Α
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = 11 V; V <sub>DS</sub> = 0 V	-	-	280	nA
g <sub>fs</sub>	forward transconductance	V <sub>DS</sub> = 10 V; I <sub>D</sub> = 15.0 A	-	19	-	S
R <sub>DS(on)</sub>	drain-source on-state resistance	$V_{GS} = V_{GS(th)} + 3.75 \text{ V}; I_D = 10.5 \text{ A}$	-	55	85	mΩ

#### Table 8. RF characteristics

Test signal: 1-carrier W-CDMA; PAR = 9.6 dB at 0.01 % probability on the CCDF; 3GPP test model 1; 1 to 64 DPCH;  $f_1$  = 1807.5 MHz;  $f_2$  = 1877.5 MHz; RF performance at  $V_{DS}$  = 32 V;  $I_{Dq}$  = 800 mA (main);  $V_{GS(amp)peak}$  = 0.4 V;  $T_{case}$  = 25 °C; unless otherwise specified; in an asymmetrical Doherty production test circuit in 1805 MHz to 1880 MHz frequency range.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
G <sub>p</sub>	power gain	P <sub>L(AV)</sub> = 85 W	14.5	15.5	-	dB
RLin	input return loss	P <sub>L(AV)</sub> = 85 W	-	-11	-7	dB
$\eta_{D}$	drain efficiency	P <sub>L(AV)</sub> = 85 W	40	44	-	%
ACPR	adjacent channel power ratio	P <sub>L(AV)</sub> = 85 W	-	-31	-27	dBc
PARO	output peak-to-average ratio	P <sub>L(AV)</sub> = 100 W	6.0	6.7	-	dB
P <sub>L(M)</sub>	peak output power	P <sub>L(AV)</sub> = 100 W	400	475	-	W

BLC8G20LS-400AV

### 8. Test information

#### 8.1 Ruggedness in Doherty operation

The BLC8G20LS-400AV is capable of withstanding a load mismatch corresponding to VSWR = 10 : 1 through all phases under the following conditions:

- V<sub>DS</sub> = 28 V; I<sub>Dq</sub> = 800 mA; V<sub>GS(amp)peak</sub> = 0.4 V; f = 1807.5 MHz: 1-carrier W-CDMA; P<sub>L</sub> = 141 W (5 dB OBO); 100 % clipping
- V<sub>DS</sub> = 32 V; I<sub>Dq</sub> = 800 mA; V<sub>GS(amp)peak</sub> = 0.4 V; f = 1807.5 MHz: 1-carrier W-CDMA; P<sub>L</sub> = 141 W (5 dB OBO); 100 % clipping

### 8.2 Impedance information

Table 9. Typical impedance of main device

Measured load-pull data of main device;  $I_{Dq}$  = 800 mA (main);  $V_{DS}$  = 32 V; pulsed CW ( $t_p$  = 100  $\mu$ s;  $\delta$  = 10 %).

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]	P <sub>L</sub> [2]	η <sub>D</sub> [2]	G <sub>p</sub> [2]				
(MHz)	<b>(</b> Ω <b>)</b>	<b>(</b> Ω <b>)</b>	(W)	(%)	(dB)				
Maximum	Maximum power load								
1805	1.2 – j5.2	1.3 – j4.4	252	55.9	18.0				
1840	1.2 – j5.3	1.2 – j4.5	249	55.6	18.1				
1880	1.6 – j5.9	1.2 – j4.4	245	53.1	17.9				
Maximum	drain efficiency	load							
1805	1.2 – j5.2	2.5 – j4.0	178	61.4	20.0				
1840	1.2 – j5.3	2.5 – j4.1	182	61.4	20.2				
1880	1.6 – j5.9	2.6 – j3.9	176	60.8	20.5				

<sup>[1]</sup>  $Z_S$  and  $Z_L$  defined in Figure 1.

#### Table 10. Typical impedance of peak device

Measured load-pull data of peak device;  $I_{Dq}$  = 1750 mA (peak);  $V_{DS}$  = 32 V; pulsed CW ( $t_p$  = 100  $\mu$ s;  $\delta$  = 10 %).

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]	P <sub>L</sub> [2]	η <sub>D</sub> [2]	G <sub>p</sub> [2]				
(MHz)	<b>(</b> Ω <b>)</b>	<b>(</b> Ω <b>)</b>	(W)	(%)	(dB)				
Maximum	Maximum power load								
1805	1.2 – j5.0	2.1 – j5.4	394	50.8	19.0				
1840	1.5 – j5.3	2.5 – j5.3	383	53.5	19.5				
1880	2.0 - j5.9	2.3 – j5.5	378	52.1	19.4				
Maximum	drain efficiency	load							
1805	1.2 – j5.0	2.5 – j3.8	289	57.8	21.4				
1840	1.5 – j5.3	2.7 – j3.7	289	59.4	21.4				
1880	2.0 - j5.9	2.4 – j3.8	284	60.4	21.7				

<sup>[1]</sup>  $Z_S$  and  $Z_L$  defined in Figure 1.

<sup>[2]</sup> At 3 dB gain compression.

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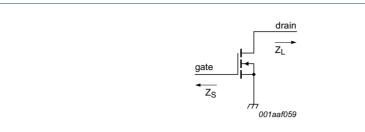


Fig 1. Definition of transistor impedance

## 8.3 Recommended impedances for Doherty design

#### Table 11. Typical impedance of main at 1:1 load

Measured load-pull data of main device;  $I_{Dq}$  = 800 mA (main);  $V_{DS}$  = 32 V; pulsed CW ( $t_p$  = 100  $\mu$ s;  $\delta$  = 10 %).

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]	P <sub>L(3dB)</sub> [2]	η <sub>D</sub> [2]	G <sub>p</sub> [2]
(MHz)	<b>(</b> Ω <b>)</b>	<b>(</b> Ω <b>)</b>	(W)	(%)	(dB)
1805	1.0 – j4.8	1.8 – j4.9	179	50.4	18.1
1840	1.1 – j5.0	1.7 – j4.6	189	51.6	18.3
1880	1.4 – j5.2	1.7 – j4.3	183	49.3	18.5

<sup>[1]</sup>  $Z_S$  and  $Z_L$  defined in Figure 1.

Table 12. Typical impedance of main device at 1: 2.5 load

Measured load-pull data of main device;  $I_{Dq}$  = 800 mA (main);  $V_{DS}$  = 32 V; pulsed CW ( $t_p$  = 100  $\mu$ s;  $\delta$  = 10 %).

f	Z <sub>S</sub> [1]	Z <sub>L</sub> [1]	P <sub>L(3dB)</sub> [2]	η <sub>D</sub> [2]	G <sub>p</sub> [2]
(MHz)	<b>(</b> Ω <b>)</b>	<b>(</b> Ω <b>)</b>	(W)	(%)	(dB)
1805	1.0 – j4.8	3.1 – j3.5	132	51.1	19.7
1840	1.1 – j5.0	3.3 – j4.0	126	50.5	19.9
1880	1.4 – j5.2	3.3 – j4.2	126	50.7	19.9

<sup>[1]</sup>  $Z_S$  and  $Z_L$  defined in Figure 1.

Table 13. Typical impedance of peak device at 1:1 load

Measured load-pull data of peak device;  $I_{Dq}$  = 1750 mA (peak);  $V_{DS}$  = 32 V; pulsed CW ( $t_p$  = 100  $\mu$ s;  $\delta$  = 10 %).

f	<b>Z</b> <sub>S</sub> [1]	Z <sub>L</sub> [1]	P <sub>L(3dB)</sub> [2]	η <sub>D</sub> [2]	G <sub>p</sub> [2]
(MHz)	<b>(</b> Ω <b>)</b>	<b>(</b> Ω <b>)</b>	(W)	(%)	(dB)
1805	1.2 – j5.0	2.8 – j4.8	316	50.0	19.0
1840	1.5 – j5.3	2.7 – j4.6	313	51.4	19.4
1880	2.0 - j5.9	2.6- j4.3	290	52.9	20.0

<sup>[1]</sup>  $Z_S$  and  $Z_L$  defined in Figure 1.

<sup>[2]</sup> At  $P_{L(AV)} = 85 \text{ W}$ .

<sup>[2]</sup> At  $P_{L(AV)} = 85 \text{ W}$ .

<sup>[2]</sup> At  $P_{L(AV)} = 85 \text{ W}$ .

Table 14. Off-state impedances of peak device

f	Z <sub>off</sub>
(MHz)	$(\Omega)$
1805	0.9 – j0.2
1840	0.9 – j0.1
1880	0.9 – j0.2

### 8.4 Test circuit

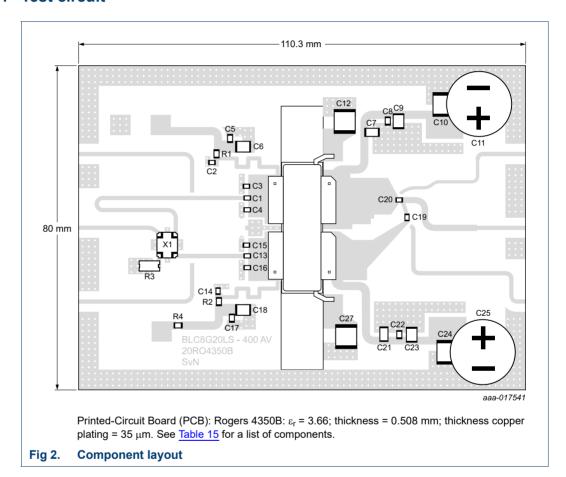


Table 15. List of components

See Figure 2 for component layout.

Component	Description	Value		Remarks
C1, C2, C13, C14, C19	multilayer ceramic chip capacitor	10 pF	[1]	ATC 100A
C3, C15	multilayer ceramic chip capacitor	2.2 pF	[1]	ATC 100A
C4, C16	multilayer ceramic chip capacitor	2.0 pF	[1]	ATC 100A
C5, C8, C17, C22	multilayer ceramic chip capacitor	100 nF	[2]	Murata
C6, C9, C18, C23	multilayer ceramic chip capacitor	4.7 μF	[2]	Murata
C7, C21	multilayer ceramic chip capacitor	10 pF	[3]	ATC 100B
C10, C24	multilayer ceramic chip capacitor	10 μF, 50 V		TDK C5750X7

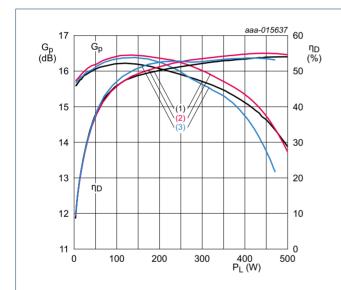
**Table 15.** List of components ...continued See Figure 2 for component layout.

Component	nent Description		Remarks	
C11; C25	electrolytic capacitor	470 μF, 63 V	Vishay 148RUS	
C12; C26	multilayer ceramic chip capacitor	4.7 μF, 100 V	TDK C5750X7	
C20	multilayer ceramic chip capacitor	5.6 pF		
R1, R2	SMD resistor	4.7 Ω	SMD 0805	
R3	SMD resistor	50 Ω	SMD 0805	
R4	SMD resistor	470 Ω	SMD 0805	
X1	directional coupler	5 dB	Anaren X3C19P1-05S	

- [1] American Technical Ceramics type 100A or capacitor of same quality.
- [2] Murata or capacitor of same quality.
- [3] American Technical Ceramics type 100B or capacitor of same quality.

### 8.5 Graphical data

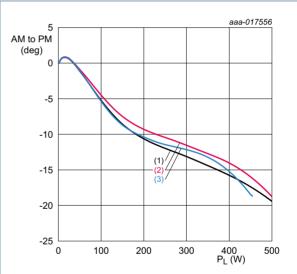
#### 8.5.1 Pulsed CW



 $V_{DS}=32$  V;  $I_{Dq}$  = 800 mA;  $V_{GS(amp)peak}$  = 0.4 V;  $t_p$  = 100  $\mu s;$   $\delta$  = 10 %.

- (1) f = 1807.5 MHz
- (2) f = 1842.5 MHz
- (3) f = 1877.5 MHz

Fig 3. Power gain and drain efficiency as function of output power; typical values



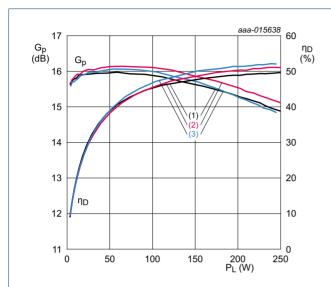
 $V_{DS} = 32 \text{ V}; I_{Dq} = 800 \text{ mA}; V_{GS(amp)peak} = 0.4 \text{ V}.$ 

- (1) f = 1807.5 MHz
- (2) f = 1842.5 MHz
- (3) f = 1877.5 MHz

Fig 4. AM to PM as a function of output power; typical values

#### 8.5.2 1-Carrier W-CDMA

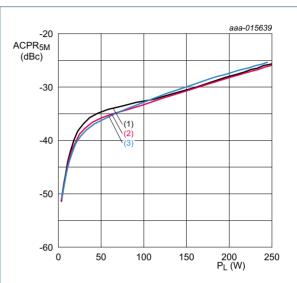
PAR = 9.6 dB per carrier at 0.01 % probability on the CCDF; 3GPP test model 1 with 64 DPCH (100 % clipping).



 $V_{DS}$  = 32 V;  $I_{Dq}$  = 800 mA;  $V_{GS(amp)peak}$  = 0.4 V.

- (1) f = 1807.5 MHz
- (2) f = 1842.5 MHz
- (3) f = 1877.5 MHz

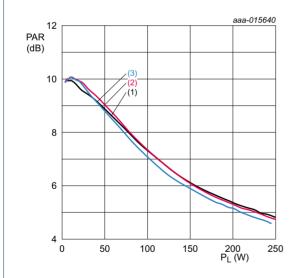
Fig 5. Power gain and drain efficiency as function of output power; typical values



 $V_{DS} = 32 \text{ V}; I_{Dq} = 800 \text{ mA}; V_{GS(amp)peak} = 0.4 \text{ V}.$ 

- (1) f = 1807.5 MHz
- (2) f = 1842.5 MHz
- (3) f = 1877.5 MHz

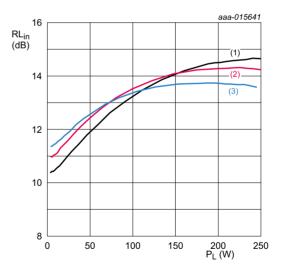
Fig 6. Adjacent channel power ratio (5 MHz) as a function of output power; typical values



 $V_{DS}$  = 32 V;  $I_{Dq}$  = 800 mA;  $V_{GS(amp)peak}$  = 0.4 V.

- (1) f = 1807.5 MHz
- (2) f = 1842.5 MHz
- (3) f = 1877.5 MHz

Fig 7. Peak-to-average power ratio as a function of output power; typical values



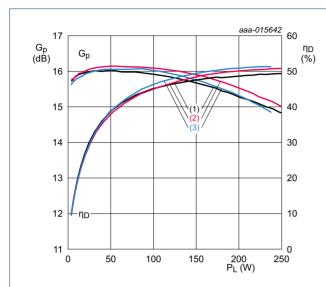
 $V_{DS} = 32 \text{ V}; I_{Dq} = 800 \text{ mA}; V_{GS(amp)peak} = 0.4 \text{ V}.$ 

- (1) f = 1807.5 MHz
- (2) f = 1842.5 MHz
- (3) f = 1877.5 MHz

Fig 8. Input return loss as a function of output power; typical values

#### 8.5.3 2-Carrier W-CDMA

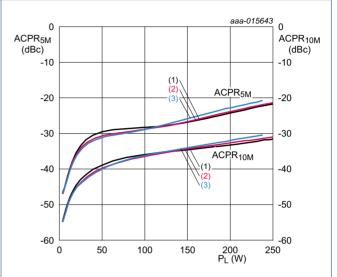
PAR = 9.6 dB at 0.01 % probability on the CCDF; 3GPP test model 1 with 64 DPCH (46 % clipping).



 $V_{DS} = 32 \text{ V}; I_{Dq} = 800 \text{ mA}; V_{GS(amp)peak} = 0.4 \text{ V}.$ 

- (1) f = 1807.5 MHz
- (2) f = 1842.5 MHz
- (3) f = 1877.5 MHz

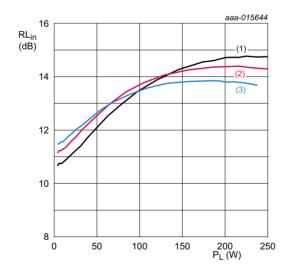
Fig 9. Power gain and drain efficiency as function of output power; typical values



 $V_{DS} = 32 \text{ V}; I_{Dq} = 800 \text{ mA}; V_{GS(amp)peak} = 0.4 \text{ V}.$ 

- (1) f = 1807.5 MHz
- (2) f = 1842.5 MHz
- (3) f = 1877.5 MHz

Fig 10. Adjacent channel power ratio (5 MHz) and adjacent channel power ratio (10 MHz) as function of output power; typical values



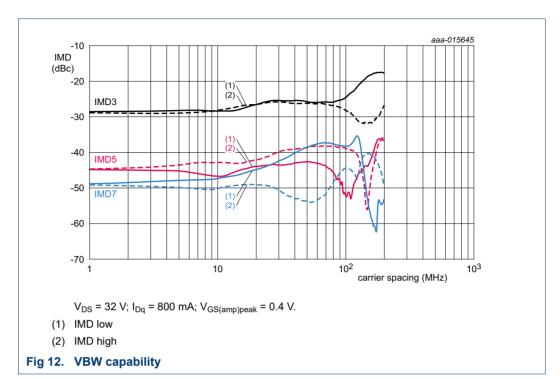
 $V_{DS} = 32 \text{ V}; I_{Dq} = 800 \text{ mA}; V_{GS(amp)peak} = 0.4 \text{ V}.$ 

- (1) f = 1807.5 MHz
- (2) f = 1842.5 MHz
- (3) f = 1877.5 MHz

Fig 11. Input return loss as a function of output power; typical values

BLC8G20LS-400AV

#### 8.5.4 2-Tone VBW



# 9. Package outline

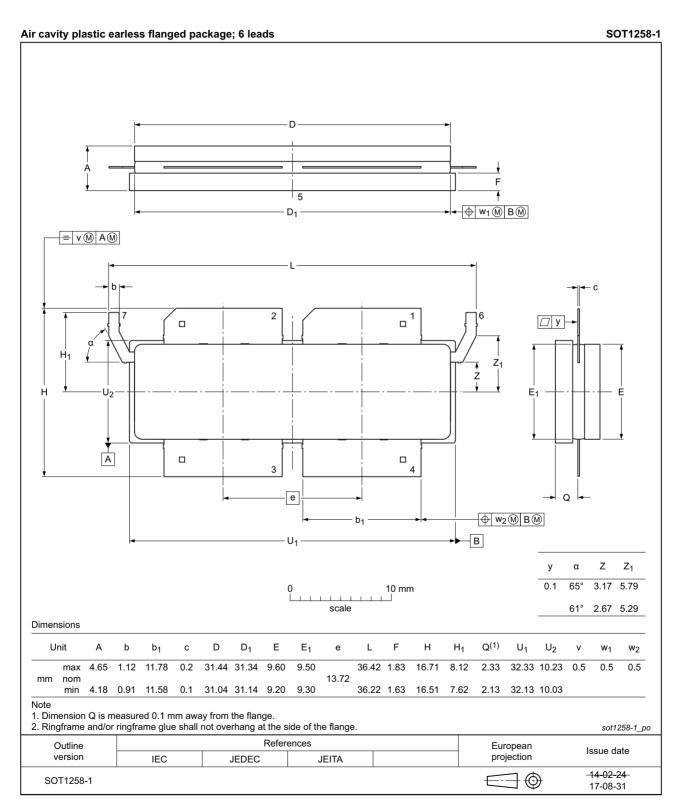


Fig 13. Package outline SOT1258-1

# 10. Handling information

#### **CAUTION**



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A or equivalent standards.

Table 16. ESD sensitivity

ESD model	Class
Charged Device Model (CDM); According to ANSI/ESDA/JEDEC standard JS-002	C2A [1]
Human Body Model (HBM); According to ANSI/ESDA/JEDEC standard JS-001	2 [2]

- [1] CDM classification C2A is granted to any part that passes after exposure to an ESD pulse of 500 V, but fails after exposure to an ESD pulse of 750 V.
- [2] HBM classification 2 is granted to any part that passes after exposure to an ESD pulse of 2000 V, but fails after exposure to an ESD pulse of 4000 V.

### 11. Abbreviations

Table 17. Abbreviations

Acronym	Description
3GPP	3rd Generation Partnership Project
AM	Amplitude Modulation
CCDF	Complementary Cumulative Distribution Function
CW	Continuous Wave
DPCH	Dedicated Physical CHannel
ESD	ElectroStatic Discharge
LDMOS	Laterally Diffused Metal-Oxide Semiconductor
MTF	Median Time to Failure
ОВО	Output Back Off
PAR	Peak-to-Average Ratio
PM	Phase Modulation
SMD	Surface Mounted Device
VBW	Video BandWidth
VSWR	Voltage Standing Wave Ratio
W-CDMA	Wideband Code Division Multiple Access

# 12. Revision history

#### Table 18. Revision history

	- ,				
Document ID	Release date	Data sheet status	Change notice	Supersedes	
BLC8G20LS-400AV v.4	20171124	Product data sheet	-	BLC8G20LS-400AV v.3	
Modifications:		<ul> <li><u>Table 2 on page 2</u>: changed simplified version drawing SOT1258-3 to SOT1258-1</li> <li><u>Table 3 on page 2</u>: changed version SOT1258-3 to SOT1258-1</li> </ul>			
		page 11: changed package o		258-3 to SOT1258-1	
BLC8G20LS-400AV v.3	20161202	Product data sheet	-	BLC8G20LS-400AV v.2	
BLC8G20LS-400AV v.2	20150901	Product data sheet	-	BLC8G20LS-400AV v.1	
BLC8G20LS-400AV v.1	20150326	Product data sheet	-	-	

# 13. Legal information

#### 13.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions"
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# **BLC8G20LS-400AV**

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# **BLC8G20LS-400AV**

#### **Power LDMOS transistor**

# 15. Contents

1	Product profile
1.1	General description 1
1.2	Features and benefits
1.3	Applications
2	Pinning information
3	Ordering information
4	Limiting values
5	Recommended operating conditions 2
6	Thermal characteristics 3
7	Characteristics
8	Test information 4
8.1	Ruggedness in Doherty operation 4
8.2	Impedance information 4
8.3	Recommended impedances for Doherty design 5
8.4	Test circuit 6
8.5	Graphical data
8.5.1	Pulsed CW
8.5.2	1-Carrier W-CDMA 8
8.5.3	2-Carrier W-CDMA 9
8.5.4	2-Tone VBW
9	Package outline
10	Handling information 12
11	Abbreviations
12	Revision history
13	Legal information
13.1	Data sheet status
13.2	Definitions14
13.3	Disclaimers
13.4	Trademarks15
14	Contact information
15	Contents

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